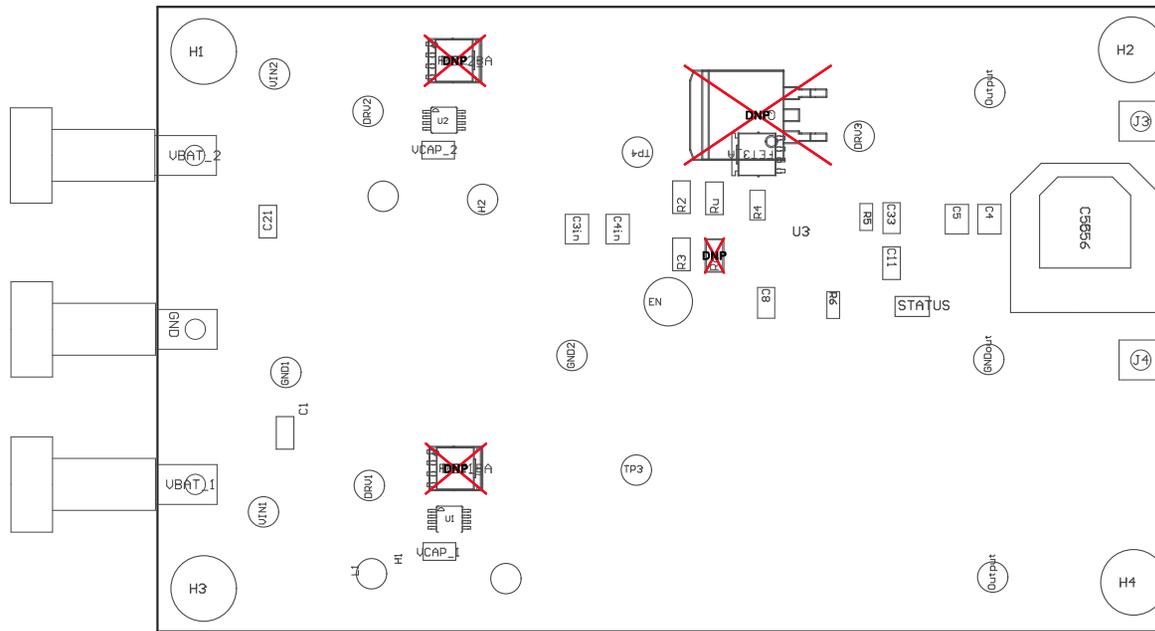
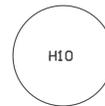
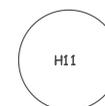
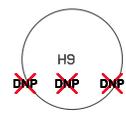


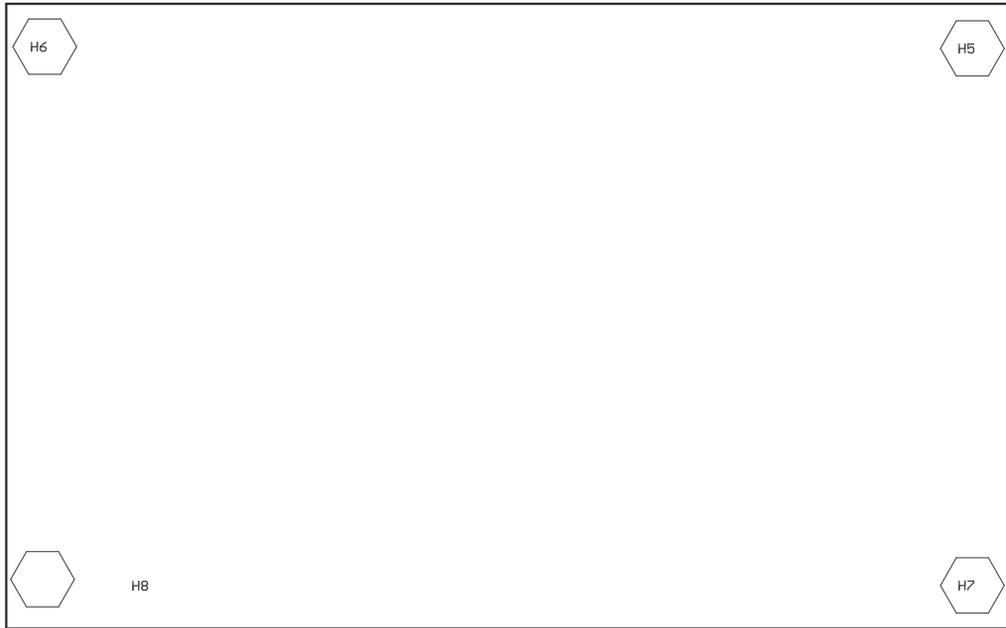
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

| | | | |
|----------------------------------|-----------------------|------------|--------------------------------|
| PCB VIEWED FROM TOP SIDE | BOARD #: PMP10748 | REV: E1 | SUN REV: Not In VersionControl |
| | | | |
| PLOT NAME = Top Assembly Drawing | GENERATED : 9/17/2015 | 6:33:48 PM | TEXAS INSTRUMENTS |



Z24 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
 Z23 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not permitted.
 Z22 ■ These assemblies are ESD-sensitive, ESD precautions shall be observed.





COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT:001

| | | | |
|-------------------------------------|----------------------------------|-------------------|--------------------------------|
| PCB VIEWED FROM BOTTOM SIDE | BOARD #: PMP10748 | REV: E1 | SUN REV: Not In VersionControl |
| | | | |
| PLOT NAME = Bottom Assembly Drawing | GENERATED : 9/17/2015 6:33:49 PM | TEXAS INSTRUMENTS | |

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